Dylan Cheung

SOFTWARE ENGINEER

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SKILLS

Programming Languages
TypeScript
JavaScript
Python
Swift
Java
C++
C

Frameworks
Mustache
Angular
Node.js
HTML
CSS

Hardware Controllers
Embedded Linux
Beagle Bone
Arduino

Other
Unity

HONORS AND AWARDS

Rensselaer Leadership Award
Dean's List

ACTIVITIES

Theta Xi Fraternity – CTO
JDRF - Ride to Cure T1D
RPISEC/INTROSEC
RPI Club Lacrosse

WORK EXPERIENCE

Surefluence Inc. Summer 2018 - Present
Junior Software Engineer Troy, NY

- Collaborated on the development of Surefluence's distributed crawler platform during their MVP product stage.
- Led development using the SCRUM methodology for a scalable data-ingest service/pipeline in Node.js over Redis with highly optimized and normalized schemas in PostgreSQL.
- Produced highly-transparent analytic insights over web-sockets with a strong emphasis on the asynchronous event loop and a distributed architecture.

Rensselaer Polytechnic Institute Fall 2017
Undergraduate Researcher Troy, NY

- Instrumental in designing/producing a computer-vision subsystem for autonomous Micro Air Vehicle (MAV) operation.
- Significantly furthered overall MAV development for an international competition hosted by the American Helicopter Society.

TP Engineering Inc. Summer 2016
Intern Danbury, CT

- Gained exposure to manufacturing science and quality control through production of custom motorcycle parts via CNC machines.

EDUCATION

Rensselaer Polytechnic Institute 2015 – 2019
B.S. - Computer Science (Systems & Software) 3.19 GPA

Relevant Coursework

- Security Engineering
- Database Systems
- Principles of Software
- Software Design & Doc
- Operating Systems
- Computer Organization
- Programming Languages
- Data Structures

PROJECTS

Rensselaer Center for Open Source Fall 2018
Fullstack Developer Troy, NY

- Led efforts to migrate backend architecture to modern TypeScript with ES7 paradigms backed by high coverage unit testing.
- Streamlined frontend development through the use of intelligent lowly coupled and highly cohesive component decorators.